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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf88-i-ss

TABLE 1-2: PIC16F87/88 PINOUT DESCRIPTION

Pin Name	PDIP/ SOIC Pin#	SSOP Pin#	QFN Pin#	I/O/P Type	Buffer Type	Description
						PORTA is a bidirectional I/O port.
RA0/AN0	17	19	23			
RA0				I/O	TTL	Bidirectional I/O pin.
AN0				I	Analog	Analog input channel 0.
RA1/AN1	18	20	24			
RA1				I/O	TTL	Bidirectional I/O pin.
AN1				I	Analog	Analog input channel 1.
RA2/AN2/CVREF/VREF-	1	1	26			
RA2				I/O	TTL	Bidirectional I/O pin.
AN2				I	Analog	Analog input channel 2.
CVREF				O		Comparator VREF output.
VREF-(4)				I	Analog	A/D reference voltage (Low) input.
RA3/AN3/VREF+/C1OUT	2	2	27			
RA3				I/O	TTL	Bidirectional I/O pin.
AN3				I	Analog	Analog input channel 3.
VREF+(4)				I	Analog	A/D reference voltage (High) input.
C1OUT				O		Comparator 1 output.
RA4/AN4/T0CKI/C2OUT	3	3	28			
RA4				I/O	ST	Bidirectional I/O pin.
AN4(4)				I	Analog	Analog input channel 4.
T0CKI				I	ST	Clock input to the TMR0 timer/counter.
C2OUT				O		Comparator 2 output.
RA5/$\overline{\text{MCLR}}$/VPP	4	4	1			
RA5				I	ST	Input pin.
$\overline{\text{MCLR}}$				I	ST	Master Clear (Reset). Input/programming voltage input. This pin is an active-low Reset to the device.
VPP				P	–	Programming voltage input.
RA6/OSC2/CLKO	15	17	20			
RA6				I/O	ST	Bidirectional I/O pin.
OSC2				O	–	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode.
CLKO				O	–	In RC mode, this pin outputs CLKO signal which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
RA7/OSC1/CLKI	16	18	21			
RA7				I/O	ST	Bidirectional I/O pin.
OSC1				I	ST/CMOS(3)	Oscillator crystal input.
CLKI				I	–	External clock source input.

Legend: I = Input O = Output I/O = Input/Output P = Power
– = Not used TTL = TTL Input ST = Schmitt Trigger Input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC Oscillator mode and a CMOS input otherwise.
4: PIC16F88 devices only.
5: The CCP1 pin is determined by the CCPMX bit in Configuration Word 1 register.

TABLE 1-2: PIC16F87/88 PINOUT DESCRIPTION (CONTINUED)

Pin Name	PDIP/ SOIC Pin#	SSOP Pin#	QFN Pin#	I/O/P Type	Buffer Type	Description
						PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT/CCP1(5)	6	7	7			
RB0				I/O	TTL	Bidirectional I/O pin.
INT				I	ST(1)	External interrupt pin.
CCP1				I/O	ST	Capture input, Compare output, PWM output.
RB1/SDI/SDA	7	8	8			
RB1				I/O	TTL	Bidirectional I/O pin.
SDI				I	ST	SPI data in.
SDA				I/O	ST	I^2C™ data.
RB2/SDO/RX/DT	8	9	9			
RB2				I/O	TTL	Bidirectional I/O pin.
SDO				O	ST	SPI data out.
RX				I		AUSART asynchronous receive.
DT				I/O		AUSART synchronous detect.
RB3/PGM/CCP1(5)	9	10	10			
RB3				I/O	TTL	Bidirectional I/O pin.
PGM				I/O	ST	Low-Voltage ICSP™ Programming enable pin.
CCP1				I	ST	Capture input, Compare output, PWM output.
RB4/SCK/SCL	10	11	12			
RB4				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
SCK				I/O	ST	Synchronous serial clock input/output for SPI.
SCL				I	ST	Synchronous serial clock Input for I^2C.
RB5/$\overline{SS}$/TX/CK	11	12	13			
RB5				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
$\overline{SS}$				I	TTL	Slave select for SPI in Slave mode.
TX				O		AUSART asynchronous transmit.
CK				I/O		AUSART synchronous clock.
RB6/AN5/PGC/T1OSO/ T1CKI	12	13	15			
RB6				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
AN5(4)				I		Analog input channel 5.
PGC				I/O	ST(2)	In-Circuit Debugger and programming clock pin.
T1OSO				O	ST	Timer1 oscillator output.
T1CKI				I	ST	Timer1 external clock input.
RB7/AN6/PGD/T1OSI	13	14	16			
RB7				I/O	TTL	Bidirectional I/O pin. Interrupt-on-change pin.
AN6(4)				I		Analog input channel 6.
PGD				I	ST(2)	In-Circuit Debugger and ICSP programming data pin.
T1OSI				I	ST	Timer1 oscillator input.
VSS	5	5, 6	3, 5	P	–	Ground reference for logic and I/O pins.
VDD	14	15, 16	17, 19	P	–	Positive supply for logic and I/O pins.

Legend: I = Input O = Output I/O = Input/Output P = Power
– = Not used TTL = TTL Input ST = Schmitt Trigger Input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC Oscillator mode and a CMOS input otherwise.
4: PIC16F88 devices only.
5: The CCP1 pin is determined by the CCPMX bit in Configuration Word 1 register.

REGISTER 3-1: EECON1: EEPROM ACCESS CONTROL REGISTER 1 (ADDRESS 18Ch)

R/W-x	U-0	U-0	R/W-x	R/W-x	R/W-0	R/S-0	R/S-0
EEPGD	—	—	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

bit 7 **EEPGD**: Program/Data EEPROM Select bit
1 = Accesses program memory
0 = Accesses data memory

bit 6-5 **Unimplemented:** Read as '0'

bit 4 **FREE:** EEPROM Forced Row Erase bit
1 = Erase the program memory row addressed by EEADRH:EEADR on the next WR command
0 = Perform write only

bit 3 **WRERR:** EEPROM Error Flag bit
1 = A write operation is prematurely terminated (any $\overline{\text{MCLR}}$ or any WDT Reset during normal operation)
0 = The write operation completed

bit 2 **WREN:** EEPROM Write Enable bit
1 = Allows write cycles
0 = Inhibits write to the EEPROM

bit 1 **WR:** Write Control bit
1 = Initiates a write cycle. The bit is cleared by hardware once write is complete. The WR bit can only be set (not cleared) in software.
0 = Write cycle to the EEPROM is complete

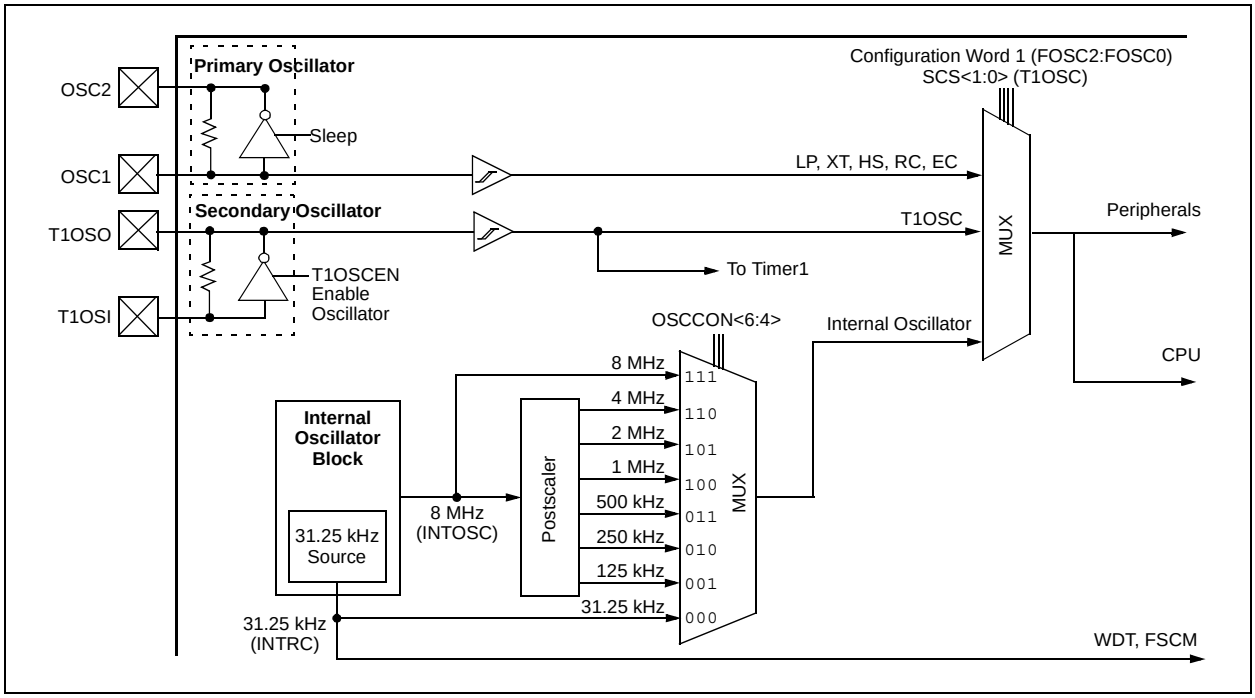
bit 0 **RD:** Read Control bit
1 = Initiates an EEPROM read, RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
0 = Does not initiate an EEPROM read

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	S = Set only
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

EXAMPLE 3-4: ERASING A FLASH PROGRAM MEMORY ROW

```
          BANKSEL  EEADRH          ; Select Bank of EEADRH
          MOVF     ADDRH, W        ;
          MOVWF    EEADRH          ; MS Byte of Program Address to Erase
          MOVF     ADDRL, W        ;
          MOVWF    EEADR           ; LS Byte of Program Address to Erase
ERASE_ROW
          BANKSEL  EECON1          ; Select Bank of EECON1
          BSF      EECON1, EEPGD   ; Point to PROGRAM memory
          BSF      EECON1, WREN    ; Enable Write to memory
          BSF      EECON1, FREE    ; Enable Row Erase operation
;
          BCF      INTCON, GIE     ; Disable interrupts (if using)
          MOVLW    55h             ;
          MOVWF    EECON2          ; Write 55h
          MOVLW    AAh             ;
          MOVWF    EECON2          ; Write AAh
          BSF      EECON1, WR      ; Start Erase (CPU stall)
          NOP                      ; Any instructions here are ignored as processor
                                   ; halts to begin Erase sequence
          NOP                      ; processor will stop here and wait for Erase complete
                                   ; after Erase processor continues with 3rd instruction
          BCF      EECON1, FREE    ; Disable Row Erase operation
          BCF      EECON1, WREN    ; Disable writes
          BSF      INTCON, GIE     ; Enable interrupts (if using)
```

FIGURE 4-6: PIC16F87/88 CLOCK DIAGRAM



4.6.4 MODIFYING THE IRCF BITS

The IRCF bits can be modified at any time regardless of which clock source is currently being used as the system clock. The internal oscillator allows users to change the frequency during run time. This is achieved by modifying the IRCF bits in the OSCCON register. The sequence of events that occur after the IRCF bits are modified is dependent upon the initial value of the IRCF bits before they are modified. If the INTRC (31.25 kHz, IRCF<2:0> = 000) is running and the IRCF bits are modified to any other value than '000', a 4 ms (approx.) clock switch delay is turned on. Code execution continues at a higher than expected frequency while the new frequency stabilizes. Time sensitive code should wait for the IOFS bit in the OSCCON register to become set before continuing. This bit can be monitored to ensure that the frequency is stable before using the system clock in time critical applications.

If the IRCF bits are modified while the internal oscillator is running at any other frequency than INTRC (31.25 kHz, IRCF<2:0> ≠ 000), there is no need for a 4 ms (approx.) clock switch delay. The new INTOSC frequency will be stable immediately after the **eight** falling edges. The IOFS bit will remain set after clock switching occurs.

Note:	Caution must be taken when modifying the IRCF bits using BCF or BSF instructions. It is possible to modify the IRCF bits to a frequency that may be out of the V_{DD} specification range; for example, V_{DD} = 2.0V and IRCF = 111 (8 MHz).

4.6.5 CLOCK TRANSITION SEQUENCE

Following are three different sequences for switching the internal RC oscillator frequency.

- Clock before switch: 31.25 kHz (IRCF<2:0> = 000)

1. IRCF bits are modified to an INTOSC/INTOSC postscaler frequency.
2. The clock switching circuitry waits for a falling edge of the current clock, at which point CLKO is held low.
3. The clock switching circuitry then waits for eight falling edges of requested clock, after which it switches CLKO to this new clock source.
4. The IOFS bit is clear to indicate that the clock is unstable and a 4 ms (approx.) delay is started. Time dependent code should wait for IOFS to become set.
5. Switchover is complete.

- Clock before switch: One of INTOSC/INTOSC postscaler (IRCF<2:0> ≠ 000)

1. IRCF bits are modified to INTRC (IRCF<2:0> = 000).
2. The clock switching circuitry waits for a falling edge of the current clock, at which point CLKO is held low.
3. The clock switching circuitry then waits for eight falling edges of requested clock, after which it switches CLKO to this new clock source.
4. Oscillator switchover is complete.

4.7.2 SEC_RUN MODE

The core and peripherals can be configured to be clocked by T1OSC using a 32.768 kHz crystal. The crystal must be connected to the T1OSO and T1OSI pins. This is the same configuration as the low-power timer circuit (see **Section 7.6 "Timer1 Oscillator"**). When SCS bits are configured to run from T1OSC, a clock transition is generated. It will clear the OSTS bit, switch the system clock from either the primary system clock or INTRC, depending on the value of SCS<1:0> and FOSC<2:0>, to the external low-power Timer1 oscillator input (T1OSC) and shut down the primary system clock to conserve power.

After a clock switch has been executed, the internal Q clocks are held in the Q1 state until eight falling edge clocks are counted on the T1OSC. After the eight clock periods have transpired, the clock input to the Q clocks is released and operation resumes (see Figure 4-8). In addition, T1RUN (In T1CON) is set to indicate that T1OSC is being used as the system clock.

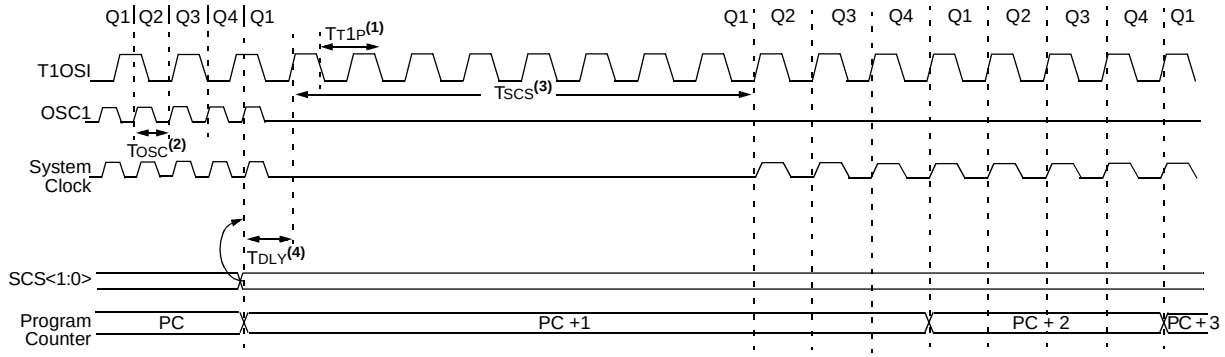
Note 1: The T1OSCEN bit must be enabled and it is the user's responsibility to ensure T1OSC is stable before clock switching to the T1OSC input clock can occur.

2: When T1OSCEN = 0, the following possible effects result.

Original SCS<1:0>	Modified SCS<1:0>	Final SCS<1:0>
00	01	00 – no change
00	11	10 – INTRC
10	11	10 – no change
10	01	00 – Oscillator defined by FOSC<2:0>

A clock switching event will occur if the final state of the SCS bits is different from the original.

FIGURE 4-8: TIMING DIAGRAM FOR SWITCHING TO SEC_RUN MODE



Note 1: TT1P = 30.52 μs.
2: TOSC = 50 ns minimum.
3: TSCS = 8 TT1P
4: TDLY = 1 TT1P.

NOTES:

REGISTER 11-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER (ADDRESS 18h)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

bit 7 **SPEN:** Serial Port Enable bit
1 = Serial port enabled (configures RB2/SDO/RX/DT and RB5/$\overline{SS}$/TX/CK pins as serial port pins)
0 = Serial port disabled

bit 6 **RX9**: 9-bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN**: Single Receive Enable bit
Asynchronous mode:
Don't care.
Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.
Synchronous mode – Slave:
Don't care.

bit 4 **CREN**: Continuous Receive Enable bit
Asynchronous mode:
1 = Enables continuous receive
0 = Disables continuous receive
Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit
Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enables interrupt and load of the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit

bit 2 **FERR**: Framing Error bit
1 = Framing error (can be updated by reading RCREG register and receive next valid byte)
0 = No framing error

bit 1 **OERR**: Overrun Error bit
1 = Overrun error (can be cleared by clearing bit CREN)
0 = No overrun error

bit 0 **RX9D:** 9th bit of Received Data (can be Parity bit, but must be calculated by user firmware)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

TABLE 11-5: INTRC BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD RATE (K)	Fosc = 8 MHz			Fosc = 4 MHz			Fosc = 2 MHz			Fosc = 1 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	—	—	0.300	0	207	0.300	0	103	0.300	0	51
1.2	1.202	+0.16	103	1.202	+0.16	51	1.202	+0.16	25	1.202	+0.16	12
2.4	2.404	+0.16	51	2.404	+0.16	25	2.404	+0.16	12	2.232	-6.99	6
9.6	9.615	+0.16	12	8.929	-6.99	6	10.417	+8.51	2	NA	—	—
19.2	17.857	-6.99	6	20.833	+8.51	2	NA	—	—	NA	—	—
28.8	31.250	+8.51	3	31.250	+8.51	1	31.250	+8.51	0	NA	—	—
38.4	41.667	+8.51	2	NA	—	—	NA	—	—	NA	—	—
57.6	62.500	+8.51	1	62.500	8.51	0	NA	—	—	NA	—	—

TABLE 11-6: INTRC BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)

BAUD RATE (K)	Fosc = 8 MHz			Fosc = 4 MHz			Fosc = 2 MHz			Fosc = 1 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	—	—	NA	—	—	NA	—	—	0.300	0	207
1.2	NA	—	—	1.202	+0.16	207	1.202	+0.16	103	1.202	+0.16	51
2.4	2.404	+0.16	207	2.404	+0.16	103	2.404	+0.16	51	2.404	+0.16	25
9.6	9.615	+0.16	51	9.615	+0.16	25	9.615	+0.16	12	8.929	-6.99	6
19.2	19.231	+0.16	25	19.231	+0.16	12	17.857	-6.99	6	20.833	+8.51	2
28.8	29.412	+2.12	16	27.778	-3.55	8	31.250	+8.51	3	31.250	+8.51	1
38.4	38.462	+0.16	12	35.714	-6.99	6	41.667	+8.51	2	NA	—	—
57.6	55.556	-3.55	8	62.500	+8.51	3	62.500	+8.51	1	62.500	+8.51	0

11.2.2 AUSART ASYNCHRONOUS RECEIVER

The receiver block diagram is shown in Figure 11-4. The data is received on the RB2/SDO/RX/DT pin and drives the data recovery block. The data recovery block is actually a high-speed shifter, operating at x16 times the baud rate; whereas, the main receive serial shifter operates at the bit rate or at FOSC.

Once Asynchronous mode is selected, reception is enabled by setting bit CREN (RCSTA<4>).

The heart of the receiver is the Receive (Serial) Shift Register (RSR). After sampling the Stop bit, the received data in the RSR is transferred to the RCREG register (if it is empty). If the transfer is complete, flag bit, RCIF (PIR1<5>), is set. The actual interrupt can be enabled/disabled by setting/clearing enable bit RCIE (PIE1<5>). Flag bit RCIF is a read-only bit which is cleared by the hardware. It is cleared when the RCREG register has been read and is empty. The RCREG is a double-buffered register (i.e., it is a two-deep FIFO). It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting to the RSR register. On the detection of the Stop bit of the third byte, if the RCREG register is still full, the Overrun Error bit, OERR (RCSTA<1>), will be set. The word in the RSR will be lost. The RCREG register can be read twice to retrieve the two bytes in the FIFO. Overrun bit OERR has to be cleared in software. This is done by resetting the receive logic (CREN is cleared and then set). If bit OERR is set, transfers from the RSR register to the RCREG register are inhibited and no further data will be received. It is, therefore, essential to clear error bit OERR if it is set. Framing Error bit, FERR (RCSTA<2>), is set if a Stop bit is detected as clear. Bit FERR and the 9th receive bit are buffered the same way as the receive data. Reading the RCREG will load bits RX9D and FERR with new values; therefore, it is essential for the user to read the RCSTA register, before reading the RCREG register, in order not to lose the old FERR and RX9D information.

FIGURE 11-4: AUSART RECEIVE BLOCK DIAGRAM

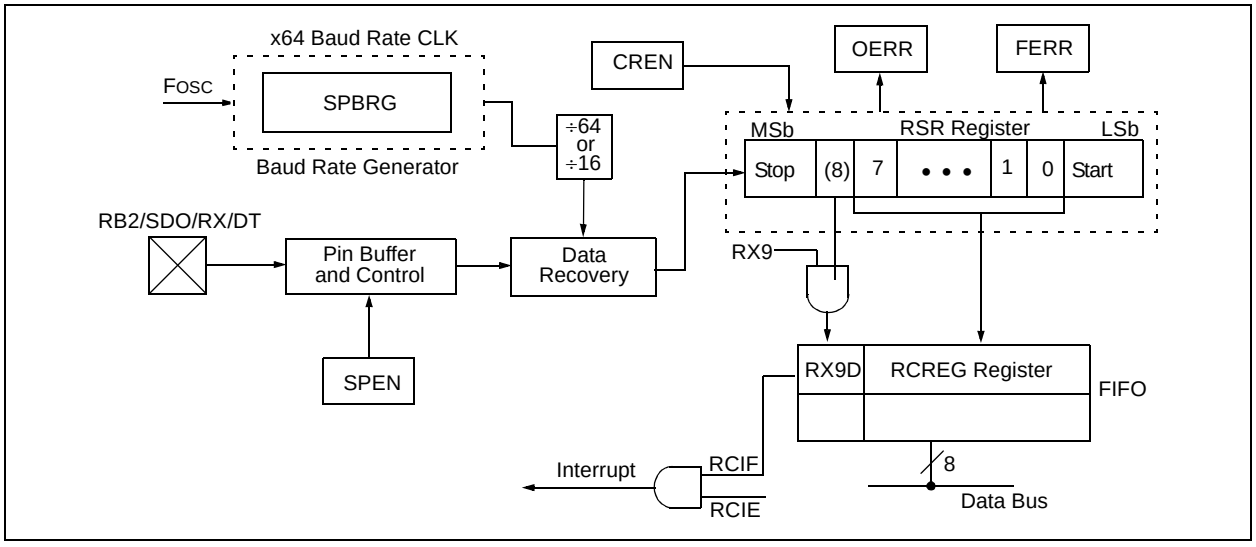
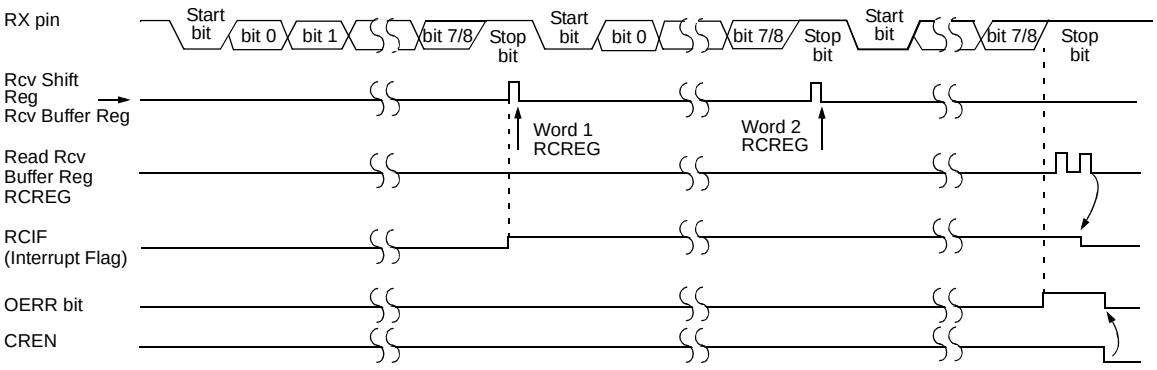


FIGURE 11-5: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (Receive Buffer) is read after the third word, causing the OERR (Overrun) bit to be set.

When setting up an asynchronous reception, follow these steps:

1. Initialize the SPBRG register for the appropriate baud rate. If a high-speed baud rate is desired, set bit BRGH (**Section 11.1 "AUSART Baud Rate Generator (BRG)"**).
2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
3. If interrupts are desired, then set enable bit RCIE.
4. If 9-bit reception is desired, then set bit RX9.
5. Enable the reception by setting bit CREN.
6. Flag bit RCIF will be set when reception is complete and an interrupt will be generated if enable bit RCIE is set.
7. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading the RCREG register.
9. If any error occurred, clear the error by clearing enable bit CREN.
10. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

TABLE 11-8: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF(1)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
1Ah	RCREG	AUSART Receive Data Register								0000 0000	0000 0000
8Ch	PIE1	—	ADIE(1)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	-000 0000	-000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for asynchronous reception.

Note 1: This bit is only implemented on the PIC16F88. The bit will read '0' on the PIC16F87.

REGISTER 15-2: CONFIG2: CONFIGURATION WORD 2 REGISTER (ADDRESS 2008h)

U-1	U-1	U-1	U-1	U-1	U-1	U-1	U-1	U-1	U-1	U-1	U-1	R/P-1	R/P-1
—	—	—	—	—	—	—	—	—	—	—	—	IESO	FCMEN
bit 13													bit 0

bit 13-2 **Unimplemented:** Read as '1'

bit 1 **IESO:** Internal External Switchover bit
1 = Internal External Switchover mode enabled
0 = Internal External Switchover mode disabled

bit 0 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor enabled
0 = Fail-Safe Clock Monitor disabled

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

15.8 Time-out Sequence

On power-up, the time-out sequence is as follows: the PWRT delay starts (if enabled) when a POR occurs. Then, OST starts counting 1024 oscillator cycles when PWRT ends (LP, XT, HS). When the OST ends, the device comes out of Reset.

If $\overline{MCLR}$ is kept low long enough, all delays will expire. Bringing $\overline{MCLR}$ high will begin execution immediately. This is useful for testing purposes, or to synchronize more than one PIC16F87/88 device operating in parallel.

Table 15-3 shows the Reset conditions for the STATUS, PCON and PC registers, while Table 15-4 shows the Reset conditions for all the registers.

15.9 Power Control/Status Register (PCON)

The Power Control/Status Register, PCON, has two bits to indicate the type of Reset that last occurred.

Bit 0 is Brown-out Reset Status bit, $\overline{BOR}$. Bit $\overline{BOR}$ is unknown on a Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if bit $\overline{BOR}$ cleared, indicating a Brown-out Reset occurred. When the Brown-out Reset is disabled, the state of the $\overline{BOR}$ bit is unpredictable.

Bit 1 is $\overline{POR}$ (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 15-1: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset		Wake-up from Sleep
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1	
XT, HS, LP	TPWRT + 1024 • TOSC	1024 • TOSC	TPWRT + 1024 • TOSC	1024 • TOSC	1024 • TOSC
EXTRC, INTRC	TPWRT	5-10 μs(1)	TPWRT	5-10 μs(1)	5-10 μs(1)
T1OSC	—	—	—	—	5-10 μs(1)

Note 1: CPU start-up is always invoked on POR, BOR and wake-up from Sleep. The 5-10 μs delay is based on a 1 MHz system clock.

TABLE 15-2: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{POR}$	$\overline{BOR}$	$\overline{TO}$	$\overline{PD}$	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
0	x	x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
1	0	1	1	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{MCLR}$ Reset during Normal Operation
1	1	1	0	$\overline{MCLR}$ Reset during Sleep or Interrupt Wake-up from Sleep

Legend: u = unchanged, x = unknown

15.14 In-Circuit Debugger

When the DEBUG bit in the Configuration Word is programmed to a '0', the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB® ICD. When the microcontroller has this feature enabled, some of the resources are not available for general use. Table 15-7 shows which features are consumed by the background debugger.

TABLE 15-7: DEBUGGER RESOURCES

I/O pins	RB6, RB7
Stack	1 level
Program Memory	Address 0000h must be NOP
	Last 100h words
Data Memory	0x070 (0x0F0, 0x170, 0x1F0) 0x1EB-0x1EF

To use the In-Circuit Debugger function of the microcontroller, the design must implement In-Circuit Serial Programming connections to RA5/MCLR/VPP, VDD, GND, RB7 and RB6. This will interface to the In-Circuit Debugger module available from Microchip, or one of the third party development tool companies.

15.15 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

15.16 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations, where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the four Least Significant bits of the ID location are used.

15.17 In-Circuit Serial Programming

PIC16F87/88 microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage (see Figure 15-13 for an example). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

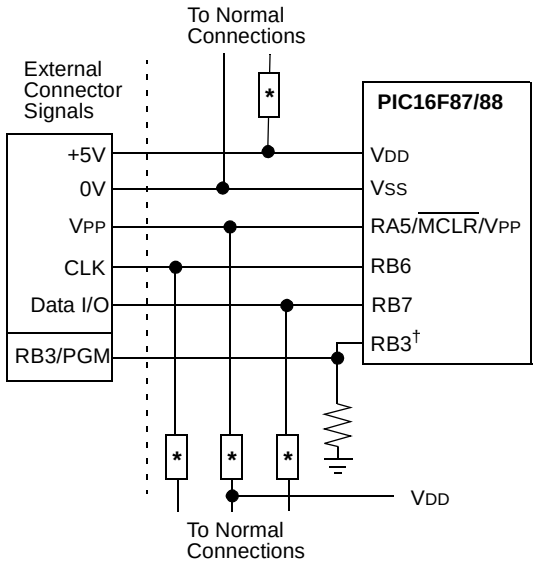
For more information on serial programming, please refer to the *"PIC16F87/88 Flash Memory Programming Specification"* (DS39607).

Note: The Timer1 oscillator shares the T1OSI and T1OSO pins with the PGD and PGC pins used for programming and debugging.

When using the Timer1 oscillator, In-Circuit Serial Programming™ (ICSP™) may not function correctly (high voltage or low voltage), or the In-Circuit Debugger (ICD) may not communicate with the controller. As a result of using either ICSP or ICD, the Timer1 crystal may be damaged.

If ICSP or ICD operations are required, the crystal should be disconnected from the circuit (disconnect either lead), or installed after programming. The oscillator loading capacitors may remain in-circuit during ICSP or ICD operation.

FIGURE 15-13: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



* Isolation devices (as required).
† RB3 only used in LVP mode.

BTFSS	Bit Test f, Skip if Set
Syntax:	[*label*] BTFSS f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b < 7
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' = 0, the next instruction is executed. If bit 'b' = 1, then the next instruction is discarded and a NOP is executed instead, making this a 2 TCY instruction.

BTFSC	Bit Test, Skip if Clear
Syntax:	[*label*] BTFSC f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' = 1, the next instruction is executed. If bit 'b', in register 'f', = 0, the next instruction is discarded and a NOP is executed instead, making this a 2 TCY instruction.

CALL	Call Subroutine
Syntax:	[*label*] CALL k
Operands:	0 ≤ k ≤ 2047
Operation:	(PC) + 1 → TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>
Status Affected:	None
Description:	Call subroutine. First, return address (PC + 1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.

CLRF	Clear f
Syntax:	[*label*] CLRF f
Operands:	0 ≤ f ≤ 127
Operation:	00h → (f), 1 → Z
Status Affected:	Z
Description:	The contents of register 'f' are cleared and the Z bit is set.

CLRW	Clear W
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W), 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT, 0 → WDT prescaler, 1 → $\overline{TO}$, 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

18.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... -0.3 to +14V
Total power dissipation **(Note 1)** 1W
Maximum current out of V_{SS} pin ..... 200 mA
Maximum current into V_{DD} pin ..... 200 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA ..... 100 mA
Maximum current sourced by PORTA ..... 100 mA
Maximum current sunk by PORTB ..... 100 mA
Maximum current sourced by PORTB ..... 100 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

2: Voltage spikes at the $\overline{MCLR}$ pin may cause latch-up. A series resistor of greater than 1 kΩ should be used to pull $\overline{MCLR}$ to V_{DD}, rather than tying the pin directly to V_{DD}.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

18.2 DC Characteristics: Power-Down and Supply Current PIC16F87/88 (Industrial, Extended) PIC16LF87/88 (Industrial) (Continued)

PIC16LF87/88 (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC16F87/88 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Supply Current (IDD)(2,3)						
	PIC16LF87/88	72	95	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (RC Oscillator)(3)
		76	90	µA	+25°C		
		76	90	µA	+85°C		
	PIC16LF87/88	138	175	µA	-40°C	VDD = 3.0V	
		136	170	µA	+25°C		
		136	170	µA	+85°C		
	All devices	310	380	µA	-40°C	VDD = 5.0V	
		290	360	µA	+25°C		
		280	360	µA	+85°C		
	Extended devices	330	500	µA	125°C		
	PIC16LF87/88	270	335	µA	-40°C	VDD = 2.0V	FOSC = 4 MHz (RC Oscillator)(3)
		280	330	µA	+25°C		
		285	330	µA	+85°C		
	PIC16LF87/88	460	610	µA	-40°C	VDD = 3.0V	
		450	600	µA	+25°C		
		450	600	µA	+85°C		
	All devices	900	1060	µA	-40°C	VDD = 5.0V	
		890	1050	µA	+25°C		
		890	1050	µA	+85°C		
	Extended devices	.920	1.5	mA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

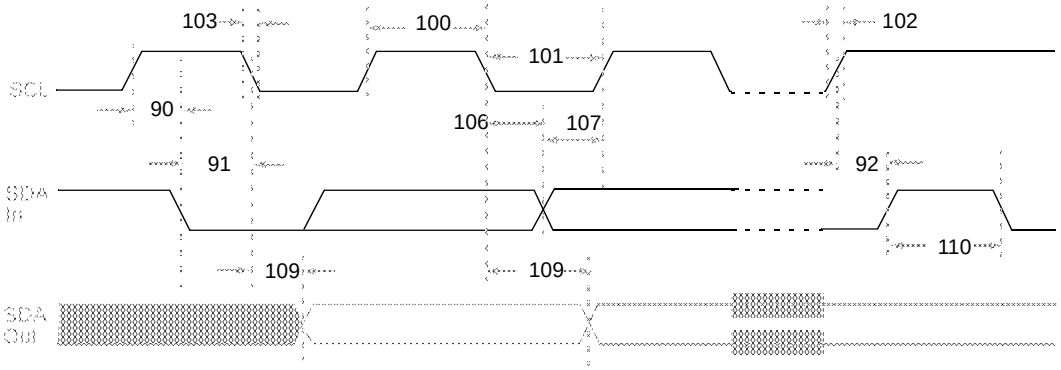
3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

TABLE 18-9: I²C™ BUS START/STOP BITS REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ	Max	Units	Conditions
90*	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	—		
91*	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	—		
92*	TSU:STO	Stop Condition Setup Time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
93	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

FIGURE 18-15: I²C™ BUS DATA TIMING

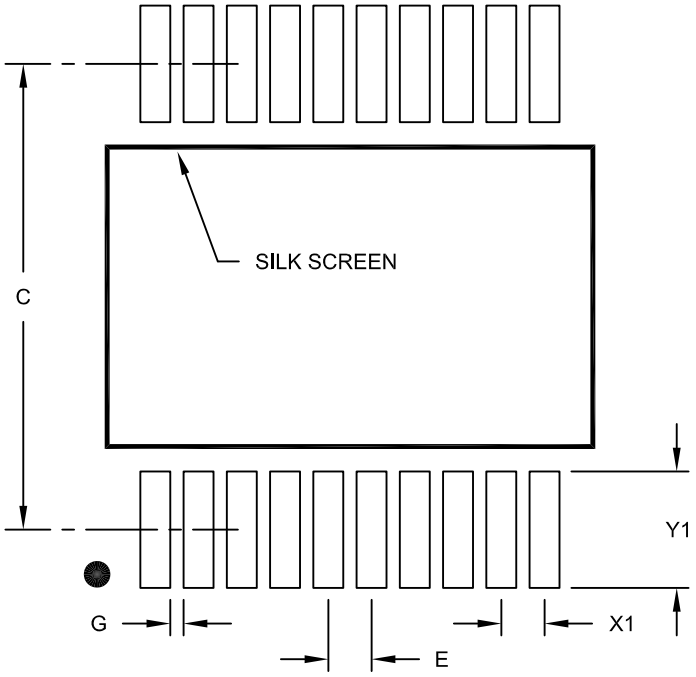


Note: Refer to Figure 18-3 for load conditions.

NOTES:

20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C		7.20	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2072A